

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Jing-En Luan</td> <td>02/09/2012</td> </tr> <tr> <td>Hk Looi</td> <td>01/30/2012</td> </tr> </tbody> </table>		Name	Execution Date	Jing-En Luan	02/09/2012	Hk Looi	01/30/2012
Name	Execution Date						
Jing-En Luan	02/09/2012						
Hk Looi	01/30/2012						
RECEIVING PARTY DATA							
Name:	STMicroelectronics Pte Ltd.						
Street Address:	28 Ang Mo Kio, Industrial Park 2						
City:	Singapore						
State/Country:	SINGAPORE						
Postal Code:	569508						
PROPERTY NUMBERS Total: 1							
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13340345</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13340345		
Property Type	Number						
Application Number:	13340345						
CORRESPONDENCE DATA							
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ATTORNEY DOCKET NUMBER:	851663.538						
NAME OF SUBMITTER:	Harold H. Bennett II						
Total Attachments: 2 source=538_ASSIGN#page1.tif source=538_ASSIGN#page2.tif							

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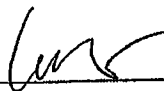
## ASSIGNMENT

WHEREAS, we, Jing-En Luan and Hk Looi (hereinafter referred to as ASSIGNORS), having mailing addresses of Blk 538 #02-4014 Ang Mo Kio Ave. 5, Singapore, Singapore 560538; and Blk 126 #06-419 Yishun St. 11, Singapore, Singapore 760126 respectively, are the joint inventors of an invention entitled "ADHESIVE DAM," as described and claimed in the specification for which an application for United States letters patent was filed on December 29, 2011, and assigned Application No. 13/340,345;

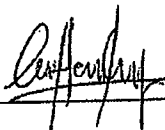
WHEREAS, STMicroelectronics Pte Ltd. (hereinafter referred to as ASSIGNEE), a corporation of the country of Singapore having a place of business at 28 Ang Mo Kio, Industrial Park 2, Singapore, Singapore 569508, is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefor in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNORS hereby sell, assign and transfer unto said ASSIGNEE the entire right, title and interest in and to said invention, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions including any extensions or adjustments in term thereof and in any and all foreign countries, and in any and all divisions, reissues and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNORS had this assignment, transfer and sale not been made. ASSIGNORS hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNORS agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding letters patent, or for the purpose of protecting title to said invention or letters patent therefor.

09/02/2012  
Date

  
Jing-En Luan

30/JAN/2012  
Date

  
Hk Looi

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